

# 74AUP1T97

Low-power configurable gate with voltage-level translator

Rev. 8 — 27 January 2022

Product data sheet

## 1. General description

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The 74AUP1T97 is a configurable multiple function gate with level translating, Schmitt-trigger inputs. The device can be configured as any of the following logic functions MUX, AND, OR, NAND, NOR, inverter and buffer; using the 3-bit input. All inputs can be connected directly to  $V_{CC}$  or GND. Low threshold Schmitt trigger inputs allow these devices to be driven by 1.8 V logic levels in 3.3 V applications. This device ensures very low static and dynamic power consumption across the entire  $V_{CC}$  range from 2.3 V to 3.6 V. This device is fully specified for partial power down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the potentially damaging backflow current through the device when it is powered down.

## 2. Features and benefits

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- Wide supply voltage range from 2.3 V to 3.6 V
- CMOS low power dissipation
- High noise immunity
- Overvoltage tolerant inputs to 3.6 V
- Low noise overshoot and undershoot < 10 % of  $V_{CC}$
- $I_{OFF}$  circuitry provides partial power-down mode operation
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Low static power consumption;  $I_{CC} = 1.5 \mu\text{A}$  (maximum)
- Complies with JEDEC standards:
  - JESD8-12 (0.8 V to 1.3 V)
  - JESD8-11 (0.9 V to 1.65 V)
  - JESD8-7 (1.65 V to 1.95 V)
  - JESD8-5 (2.3 V to 2.7 V)
  - JESD8C (2.7 V to 3.6 V)
- ESD protection:
  - HBM JESD22-A114F Class 3A exceeds 5000 V
  - MM JESD22-A115-A exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AUP1T97GW	-40 °C to +125 °C	TSSOP6	plastic thin shrink small outline package; 6 leads; body width 1.25 mm	SOT363-2
74AUP1T97GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74AUP1T97GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74AUP1T97GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74AUP1T97GX	-40 °C to +125 °C	X2SON6	plastic thermal enhanced extremely thin small outline package; no leads; 6 terminals; body 1.0 × 0.8 × 0.32 mm	SOT1255-2

### 4. Marking

Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74AUP1T97GW	59
74AUP1T97GM	59
74AUP1T97GN	59
74AUP1T97GS	59
74AUP1T97GX	59

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

### 5. Functional diagram

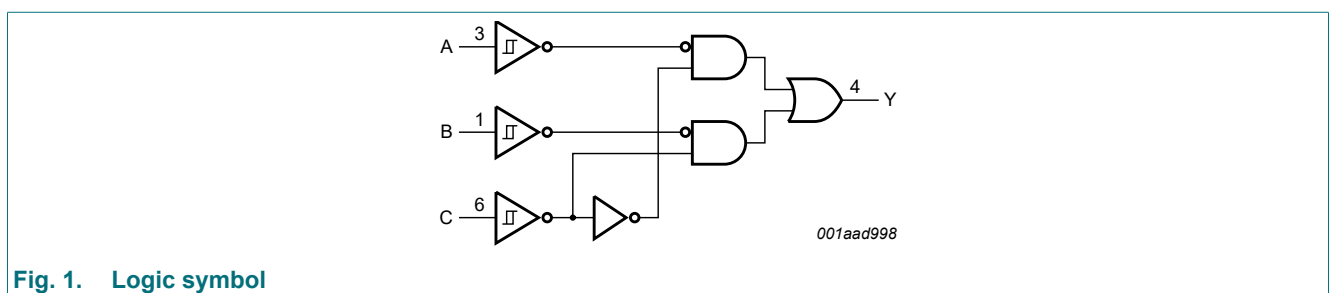


Fig. 1. Logic symbol

## 6. Pinning information

### 6.1. Pinning

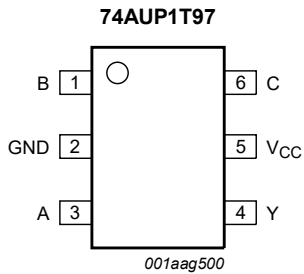


Fig. 2. Pin configuration SOT363-2 (TSSOP6)

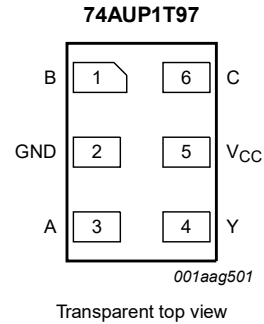


Fig. 3. Pin configuration SOT886 (XSON6)

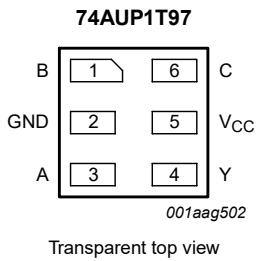


Fig. 4. Pin configuration SOT1115 and SOT1202 (XSON6)

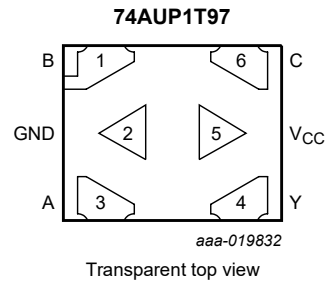


Fig. 5. Pin configuration SOT1255-2 (X2SON6)

### 6.2. Pin description

Table 3. Pin description

Symbol	Pin	Description
B	1	data input
GND	2	ground (0 V)
A	3	data input
Y	4	data output
V <sub>CC</sub>	5	supply voltage
C	6	data input

## 7. Functional description

**Table 4. Function table**

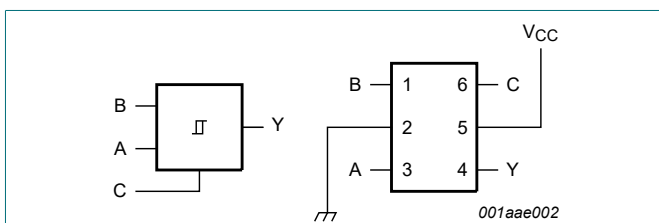
*H = HIGH voltage level; L = LOW voltage level.*

Input			Output
C	B	A	Y
L	L	L	L
L	L	H	L
L	H	L	H
L	H	H	H
H	L	L	L
H	L	H	H
H	H	L	L
H	H	H	H

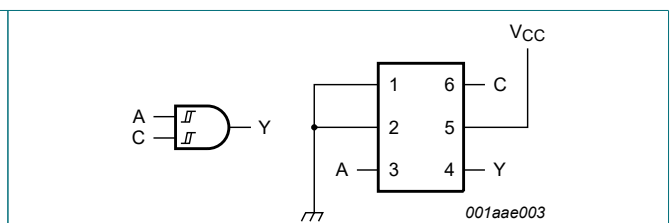
### 7.1. Logic configurations

**Table 5. Function selection table**

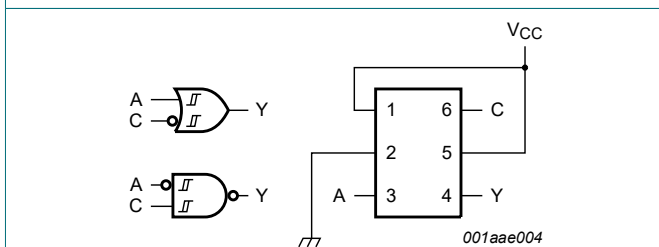
Logic function	Figure
2-input MUX	see <a href="#">Fig. 6</a>
2-input AND	see <a href="#">Fig. 7</a>
2-input OR with one input inverted	see <a href="#">Fig. 8</a>
2-input NAND with one input inverted	see <a href="#">Fig. 8</a>
2-input AND with one input inverted	see <a href="#">Fig. 9</a>
2-input NOR with one input inverted	see <a href="#">Fig. 9</a>
2-input OR	see <a href="#">Fig. 10</a>
Inverter	see <a href="#">Fig. 11</a>
Buffer	see <a href="#">Fig. 12</a>



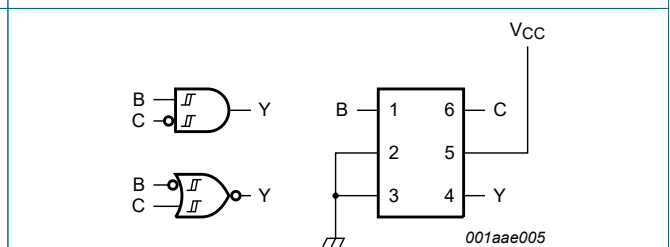
**Fig. 6. 2-input MUX**



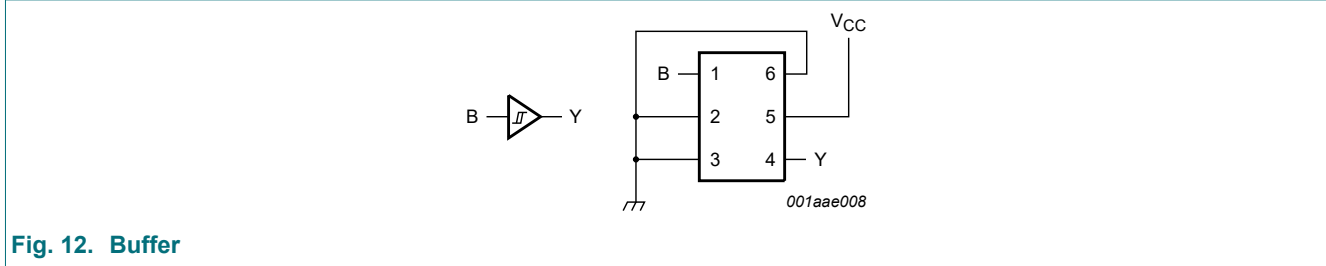
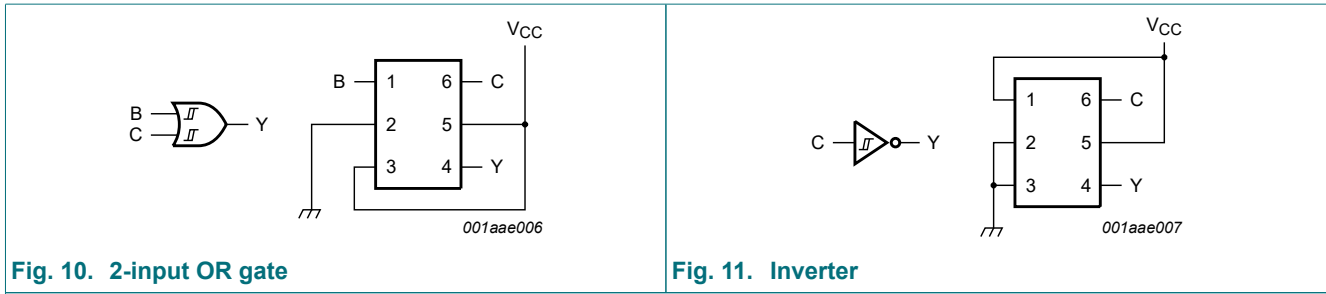
**Fig. 7. 2-input AND gate**



**Fig. 8. 2-input NAND gate with input A inverted or 2-input OR gate with input C inverted**



**Fig. 9. 2-input NOR gate with input B inverted or 2-input AND gate with input C inverted**



## 8. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+4.6	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$V_I$	input voltage		[1] -0.5	+4.6	V
$I_{OK}$	output clamping current	$V_O < 0$ V	-50	-	mA
$V_O$	output voltage	Active mode and Power-down mode	[1] -0.5	+4.6	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	±20	mA
$I_{CC}$	supply current		-	50	mA
$I_{GND}$	ground current		-50	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[2] -	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SOT363-2 (TSSOP6) package:  $P_{tot}$  derates linearly with 3.7 mW/K above 83 °C.

For SOT886 (XSON6) package:  $P_{tot}$  derates linearly with 3.3 mW/K above 74 °C.

For SOT1115 (XSON6) package:  $P_{tot}$  derates linearly with 3.2 mW/K above 71 °C.

For SOT1202 (XSON6) package:  $P_{tot}$  derates linearly with 3.3 mW/K above 74 °C.

For SOT1255-2 (X2SON6) package:  $P_{tot}$  derates linearly with 3.3 mW/K above 75 °C.

## 9. Recommended operating conditions

Table 7. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		2.3	3.6	V
$V_I$	input voltage		0	3.6	V
$V_O$	output voltage	Active mode	0	$V_{CC}$	V
		Power-down mode; $V_{CC} = 0$ V	0	3.6	V
$T_{amb}$	ambient temperature		-40	+125	°C

## 10. Static characteristics

**Table 8. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>T<sub>amb</sub> = 25 °C</b>						
V <sub>T+</sub>	positive-going threshold voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	0.60	-	1.10	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.75	-	1.16	V
V <sub>T-</sub>	negative-going threshold voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	0.35	-	0.60	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.50	-	0.85	V
V <sub>H</sub>	hysteresis voltage	(V <sub>H</sub> = V <sub>T+</sub> - V <sub>T-</sub> )				
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.23	-	0.60	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.25	-	0.56	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.3 V to 3.6 V	V <sub>CC</sub> - 0.1	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	2.05	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.9	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.72	-	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.6	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.3 V to 3.6 V	-	-	0.10	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.31	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.44	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.31	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.44	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.1	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.1	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.2	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.3 V to 3.6 V	-	-	1.2	μA
C <sub>I</sub>	input capacitance	V <sub>CC</sub> = 0 V to 3.6 V; V <sub>I</sub> = GND or V <sub>CC</sub>	-	0.8	-	pF
C <sub>O</sub>	output capacitance	V <sub>O</sub> = GND; V <sub>CC</sub> = 0 V	-	1.7	-	pF

## Low-power configurable gate with voltage-level translator

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>T<sub>amb</sub> = -40 °C to +85 °C</b>						
V <sub>T+</sub>	positive-going threshold voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	0.60	-	1.10	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.75	-	1.19	V
V <sub>T-</sub>	negative-going threshold voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	0.35	-	0.60	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.50	-	0.85	V
V <sub>H</sub>	hysteresis voltage	(V <sub>H</sub> = V <sub>T+</sub> - V <sub>T-</sub> )				
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.10	-	0.60	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.15	-	0.56	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.3 V to 3.6 V	V <sub>CC</sub> - 0.1	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	1.97	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.85	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.67	-	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.55	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.3 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.33	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.45	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.33	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.45	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.5	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.5	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.5	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.3 V to 3.6 V	-	-	1.5	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>CC</sub> = 2.3 V to 2.7 V; I <sub>O</sub> = 0 A [1]	-	-	4	μA
		V <sub>CC</sub> = 3.0 V to 3.6 V; I <sub>O</sub> = 0 A [2]	-	-	12	μA

## Low-power configurable gate with voltage-level translator

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>T<sub>amb</sub> = -40 °C to +125 °C</b>						
V <sub>T+</sub>	positive-going threshold voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	0.60	-	1.10	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.75	-	1.19	V
V <sub>T-</sub>	negative-going threshold voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	0.33	-	0.64	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.46	-	0.85	V
V <sub>H</sub>	hysteresis voltage	(V <sub>H</sub> = V <sub>T+</sub> - V <sub>T-</sub> )				
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.10	-	0.60	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.15	-	0.56	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.3 V to 3.6 V	V <sub>CC</sub> - 0.11	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	1.77	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.67	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.40	-	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.30	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.3 V to 3.6 V	-	-	0.11	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.36	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.50	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.50	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.75	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.75	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.75	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.3 V to 3.6 V	-	-	3.5	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>CC</sub> = 2.3 V to 2.7 V; I <sub>O</sub> = 0 A [1]	-	-	7	μA
		V <sub>CC</sub> = 3.0 V to 3.6 V; I <sub>O</sub> = 0 A [2]	-	-	22	μA

[1] One input at 0.3 V or 1.1 V, other input at V<sub>CC</sub> or GND.

[2] One input at 0.45 V or 1.2 V, other input at V<sub>CC</sub> or GND.



## 11. Dynamic characteristics

**Table 9. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 14.

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ [1]	Max	Min	Max	Min	Max	
<b>V<sub>CC</sub> = 2.3 V to 2.7 V; V<sub>I</sub> = 1.65 V to 1.95 V</b>										
t <sub>pd</sub>	propagation delay	A, B, C to Y; see Fig. 13 [2]								
		C <sub>L</sub> = 5 pF	2.2	3.5	5.5	0.5	6.8	0.5	7.5	ns
		C <sub>L</sub> = 10 pF	2.6	4.1	6.3	1.0	7.9	1.0	8.7	ns
		C <sub>L</sub> = 15 pF	2.9	4.6	6.9	1.0	8.7	1.0	9.6	ns
		C <sub>L</sub> = 30 pF	3.7	5.8	8.4	1.5	10.8	1.5	11.9	ns
<b>V<sub>CC</sub> = 2.3 V to 2.7 V; V<sub>I</sub> = 2.3 V to 2.7 V</b>										
t <sub>pd</sub>	propagation delay	A, B, C to Y; see Fig. 13 [2]								
		C <sub>L</sub> = 5 pF	1.8	3.4	5.5	0.5	6.0	0.5	6.6	ns
		C <sub>L</sub> = 10 pF	2.2	4.0	6.2	1.0	7.1	1.0	7.9	ns
		C <sub>L</sub> = 15 pF	2.5	4.4	6.8	1.0	7.9	1.0	8.7	ns
		C <sub>L</sub> = 30 pF	3.2	5.6	8.3	1.5	10.0	1.5	11.0	ns
<b>V<sub>CC</sub> = 2.3 V to 2.7 V; V<sub>I</sub> = 3.0 V to 3.6 V</b>										
t <sub>pd</sub>	propagation delay	A, B, C to Y; see Fig. 13 [2]								
		C <sub>L</sub> = 5 pF	1.4	3.1	5.0	0.5	5.5	0.5	6.1	ns
		C <sub>L</sub> = 10 pF	1.8	3.7	5.7	1.0	6.5	1.0	7.2	ns
		C <sub>L</sub> = 15 pF	2.2	4.2	6.3	1.0	7.4	1.0	8.2	ns
		C <sub>L</sub> = 30 pF	2.9	5.3	7.9	1.5	9.5	1.5	10.5	ns
<b>V<sub>CC</sub> = 3.0 V to 3.6 V; V<sub>I</sub> = 1.65 V to 1.95 V</b>										
t <sub>pd</sub>	propagation delay	A, B, C to Y; see Fig. 13 [2]								
		C <sub>L</sub> = 5 pF	2.1	2.9	3.9	0.5	8.0	0.5	8.8	ns
		C <sub>L</sub> = 10 pF	2.5	3.4	4.6	1.0	8.5	1.0	9.4	ns
		C <sub>L</sub> = 15 pF	2.9	3.9	5.2	1.0	9.1	1.0	10.1	ns
		C <sub>L</sub> = 30 pF	3.6	5.0	6.7	1.5	9.8	1.5	10.8	ns
<b>V<sub>CC</sub> = 3.0 V to 3.6 V; V<sub>I</sub> = 2.3 V to 2.7 V</b>										
t <sub>pd</sub>	propagation delay	A, B, C to Y; see Fig. 13 [2]								
		C <sub>L</sub> = 5 pF	1.7	2.8	4.2	0.5	5.3	0.5	5.9	ns
		C <sub>L</sub> = 10 pF	2.1	3.4	5.0	1.0	6.1	1.0	6.8	ns
		C <sub>L</sub> = 15 pF	2.4	3.8	5.6	1.0	6.8	1.0	7.5	ns
		C <sub>L</sub> = 30 pF	3.2	5.0	7.1	1.5	8.5	1.5	9.4	ns
<b>V<sub>CC</sub> = 3.0 V to 3.6 V; V<sub>I</sub> = 3.0 V to 3.6 V</b>										
t <sub>pd</sub>	propagation delay	A, B, C to Y; see Fig. 13 [2]								
		C <sub>L</sub> = 5 pF	1.4	2.7	4.2	0.5	4.7	0.5	5.2	ns
		C <sub>L</sub> = 10 pF	1.8	3.3	5.0	1.0	5.7	1.0	6.3	ns
		C <sub>L</sub> = 15 pF	2.1	3.8	5.6	1.0	6.2	1.0	6.9	ns
		C <sub>L</sub> = 30 pF	2.9	4.9	7.1	1.5	7.8	1.5	8.6	ns

Low-power configurable gate with voltage-level translator

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ [1]	Max	Min	Max	Min	Max	
<b>T<sub>amb</sub> = 25 °C</b>										
C <sub>PD</sub>	power dissipation capacitance	f <sub>i</sub> = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> [3]								
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	3.6	-	-	-	-	-	pF
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	4.3	-	-	-	-	-	pF

- [1] All typical values are measured at nominal V<sub>CC</sub>.
- [2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.
- [3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:  
 f<sub>i</sub> = input frequency in MHz;  
 f<sub>o</sub> = output frequency in MHz;  
 C<sub>L</sub> = output load capacitance in pF;  
 V<sub>CC</sub> = supply voltage in V;  
 N = number of inputs switching;  
 Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs.

11.1. Waveform and test circuit

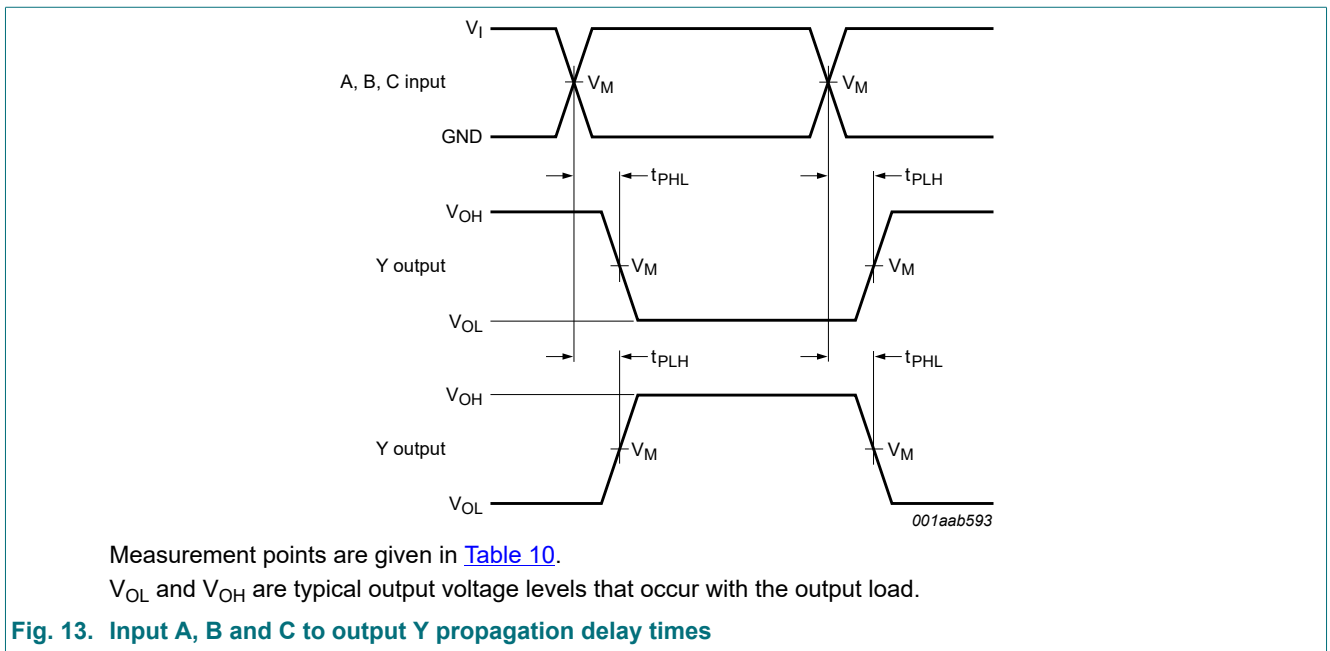
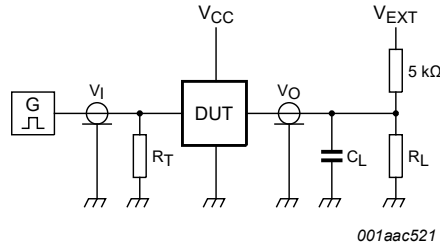


Table 10. Measurement points

Supply voltage	Input			Output
V <sub>CC</sub>	V <sub>M</sub>	V <sub>I</sub>	t <sub>r</sub> = t <sub>f</sub>	V <sub>M</sub>
2.3 V to 3.6 V	0.5 × V <sub>I</sub>	1.65 V to 3.6 V	≤ 3.0 ns	0.5 × V <sub>CC</sub>

Low-power configurable gate with voltage-level translator



001aac521

Test data is given in [Table 11](#).

Definitions test circuit:

$R_T$  = termination resistance should be equal to output impedance  $Z_o$  of the pulse generator;

$C_L$  = load capacitance including jig and probe capacitance;

$R_L$  = load resistance.

**Fig. 14. Test circuit for measuring switching times**

**Table 11. Test data**

Supply voltage	Load		$V_{EXT}$		
$V_{CC}$	$C_L$	$R_L$ [1]	$t_{PLH}$ , $t_{PHL}$	$t_{PZH}$ , $t_{PHZ}$	$t_{PZL}$ , $t_{PLZ}$
2.3 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	$2 \times V_{CC}$

[1] For measuring enable and disable times  $R_L = 5 \text{ k}\Omega$ .  
 For measuring propagation delays, setup and hold times and pulse width  $R_L = 1 \text{ M}\Omega$ .

## 12. Package outline

TSSOP6: plastic thin shrink small outline package; 6 leads; body width 1.25 mm

SOT363-2

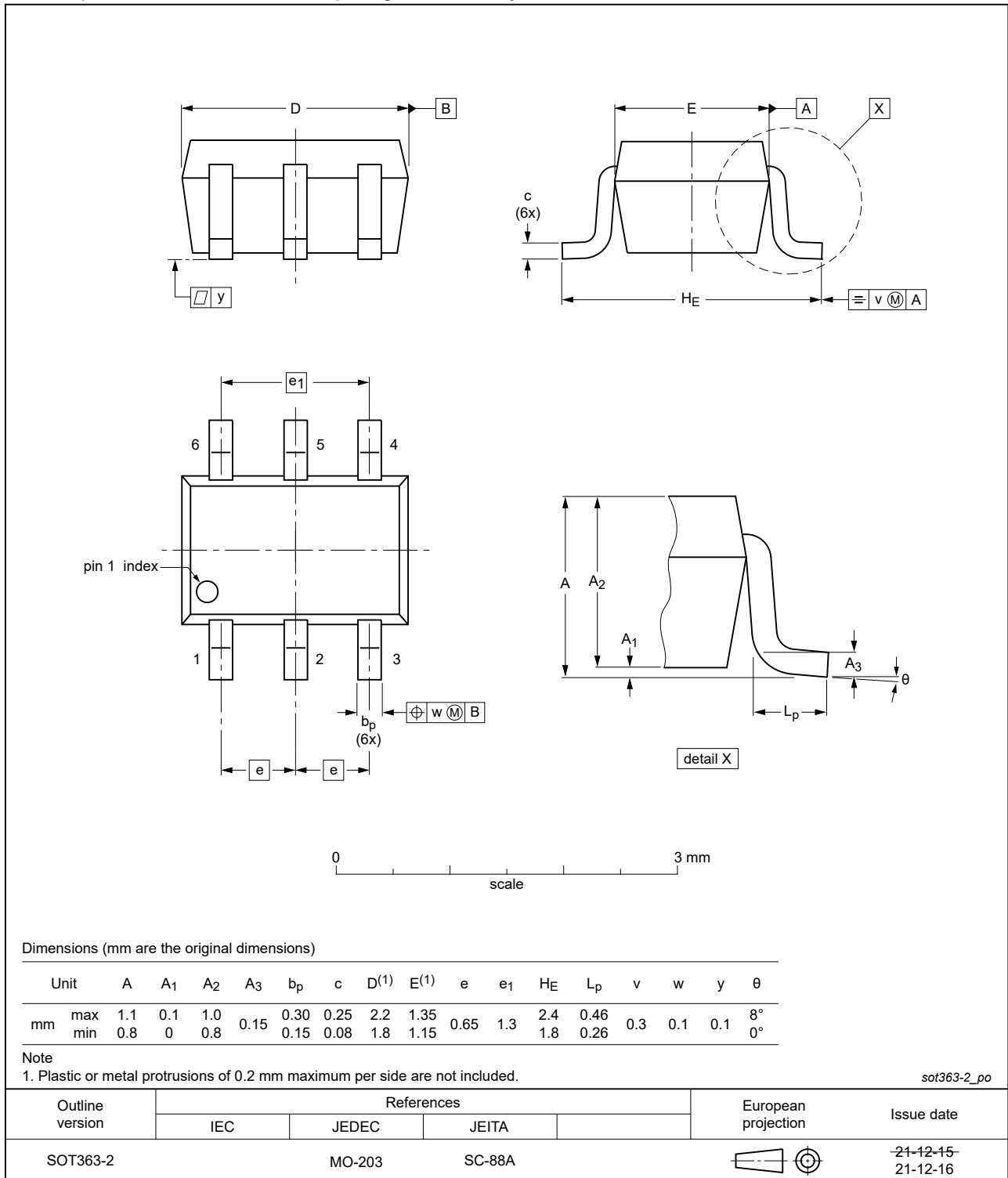


Fig. 15. Package outline SOT363-2 (TSSOP6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

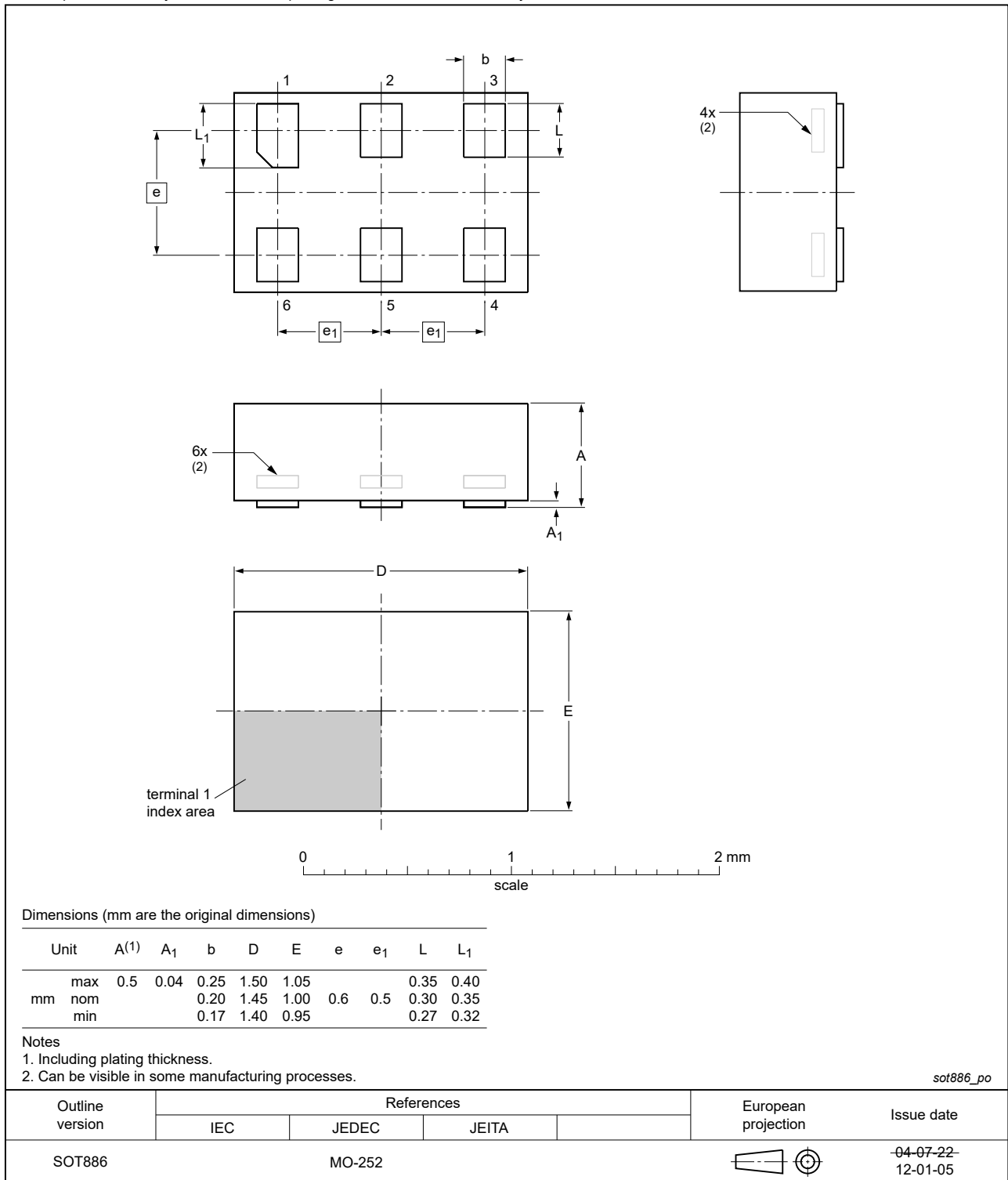


Fig. 16. Package outline SOT886 (XSON6)

XSON6: extremely thin small outline package; no leads;  
6 terminals; body 0.9 x 1.0 x 0.35 mm

SOT1115



Fig. 17. Package outline SOT1115 (XSON6)

XSON6: extremely thin small outline package; no leads;  
6 terminals; body 1.0 x 1.0 x 0.35 mm

SOT1202



Fig. 18. Package outline SOT1202 (XSON6)

X2SON6: plastic thermal enhanced extremely thin small outline package; no leads; 6 terminals; body 1.0 x 0.8 x 0.32 mm

SOT1255-2

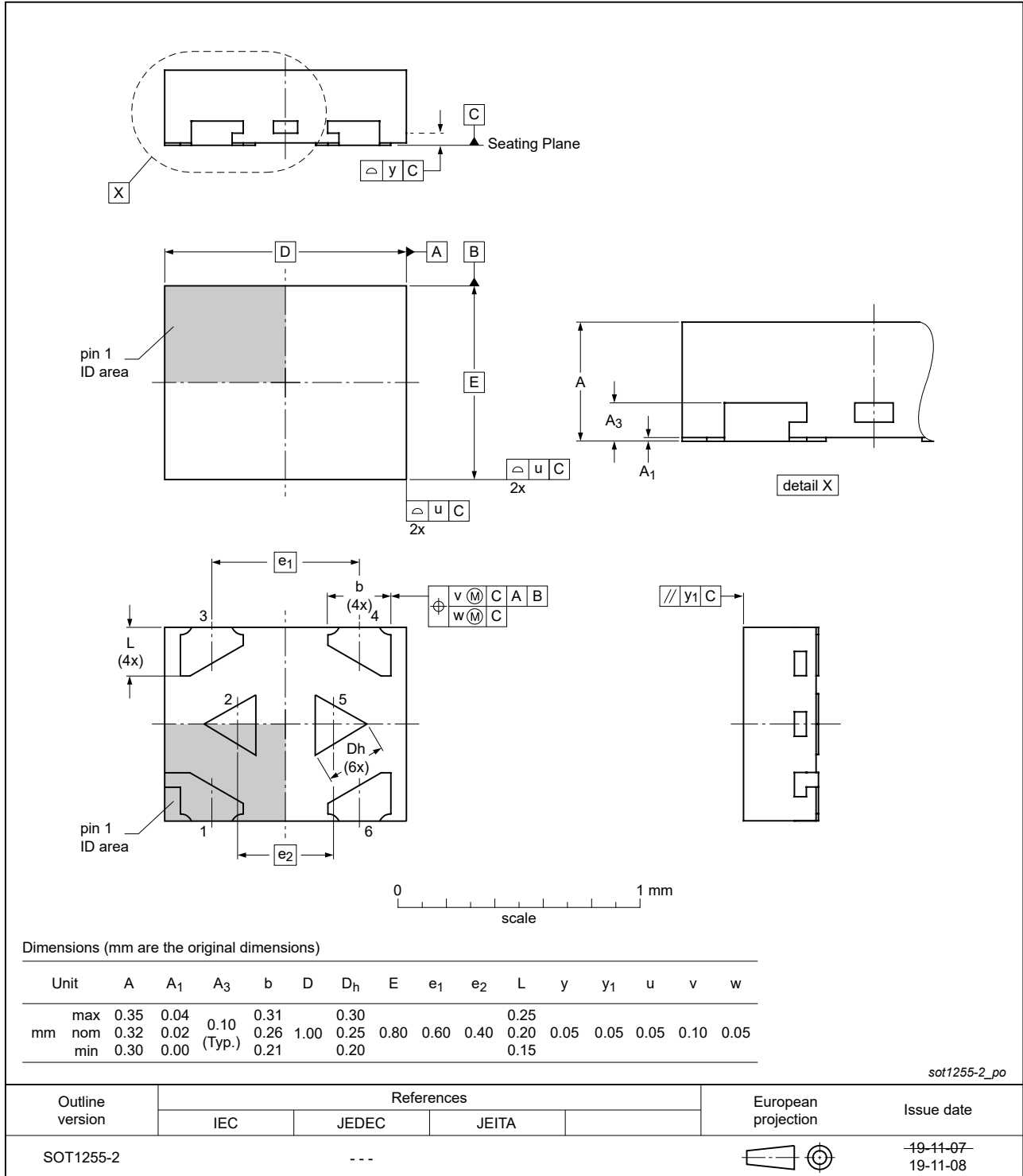


Fig. 19. Package outline SOT1255-2 (X2SON6)



## 13. Abbreviations

Table 12. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 14. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP1T97 v.8	20220127	Product data sheet	-	74AUP1T97 v.7
Modifications:	<ul style="list-style-type: none"> <li>Package SOT363 (SC-88) changed to SOT363-2 (TSSOP6).</li> </ul>			
74AUP1T97 v.7	20211104	Product data sheet	-	74AUP1T97 v.6
Modifications:	<ul style="list-style-type: none"> <li><a href="#">Section 1</a> and <a href="#">Section 2</a> updated.</li> <li>SOT1255 (X2SON6) package changed to SOT1255-2 (X2SON6) package.</li> <li>Type number 74AUP1T97GF (SOT891/XSON6) removed.</li> <li>Type number 74AUP1T97UK (SOT1454-1/WLCSP6) removed.</li> <li><a href="#">Table 6</a>: Derating values for <math>P_{tot}</math> total power dissipation updated.</li> </ul>			
74AUP1T97 v.6	20170328	Product data sheet	-	74AUP1T97 v.5
Modifications:	<ul style="list-style-type: none"> <li>Added type number 74AUP1T97UK (WLCSP6).</li> </ul>			
74AUP1T97 v.5	20150917	Product data sheet	-	74AUP1T97 v.4
Modifications:	<ul style="list-style-type: none"> <li>Added type number 74AUP1T97GX (SOT1255/X2SON6).</li> </ul>			
74AUP1T97 v.4	20120815	Product data sheet	-	74AUP1T97 v.3
Modifications:	<ul style="list-style-type: none"> <li>Package outline drawing of SOT886 (<a href="#">Fig. 16</a>) modified.</li> </ul>			
74AUP1T97 v.3	20111130	Product data sheet	-	74AUP1T97 v.2
74AUP1T97 v.2	20101018	Product data sheet	-	74AUP1T97 v.1
74AUP1T97 v.1	20071025	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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